



ALPHA & OMEGA
SEMICONDUCTOR

AOCR35101E

12V Common-Drain Dual N-Channel MOSFET

General Description

- Trench Power MOSFET technology
- Low $R_{SS(ON)}$
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS 2.0 and Halogen-Free Compliant

Applications

- Battery protection switch
- Mobile device battery charging and discharging

Product Summary

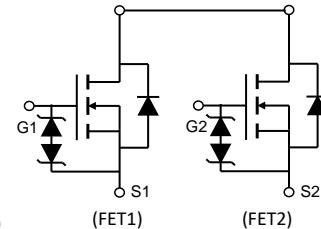
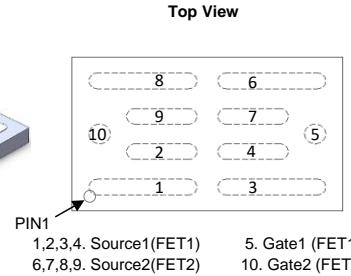
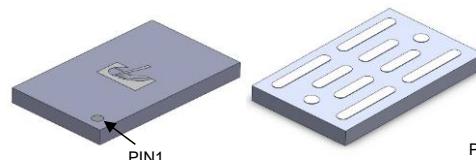
V_{SS}	12V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$)	< 1.15mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.8V$)	< 1.3mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.1V$)	< 1.6mΩ
$R_{SS(ON)}$ (at $V_{GS}=2.5V$)	< 2.2mΩ

Typical ESD protection

HBM Class 2



MRigidCSP™ 3.2x1.95_10
Top View Bottom View



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOCR35101E	MRigidCSP™3.2x1.95_10	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	V_{SS}	12	V
Gate-Source Voltage	V_{GS}	± 8	V
Source Current(DC) ^{Note1}	I_S $T_A=25^\circ C$	45	A
Source Current(Pulse) ^{Note2}	I_{SM}	47	
Power Dissipation ^{Note1}	P_D $T_A=25^\circ C$	2.8	W
Junction and Storage Temperature Range	T_J , T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient $t \leq 10s$	R_{0JA}	35	°C/W
Maximum Junction-to-Ambient Steady-State		45	°C/W

Note 1. I_S rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

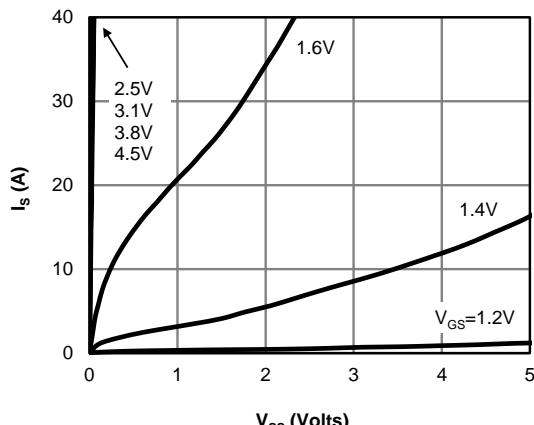
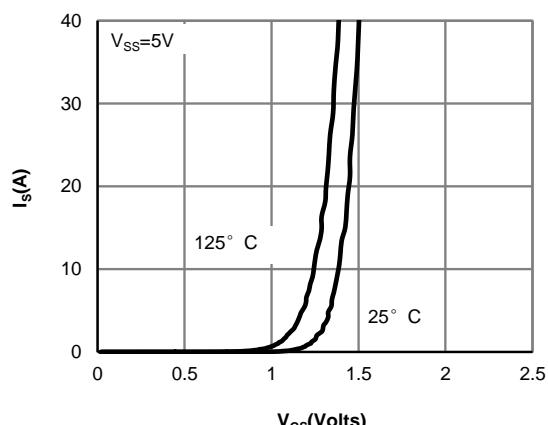
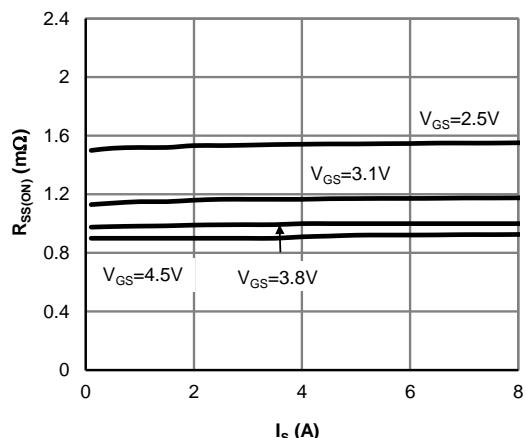
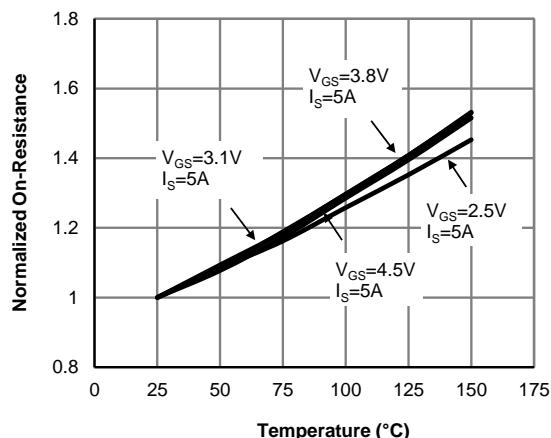
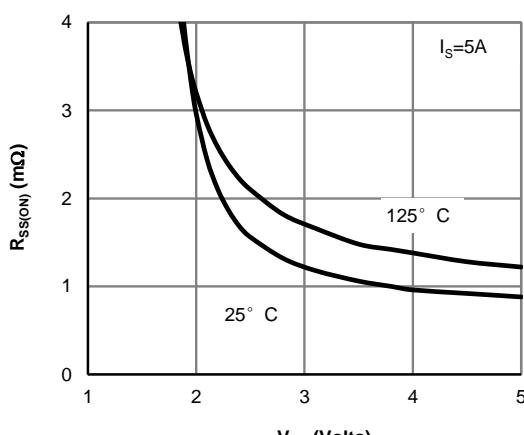
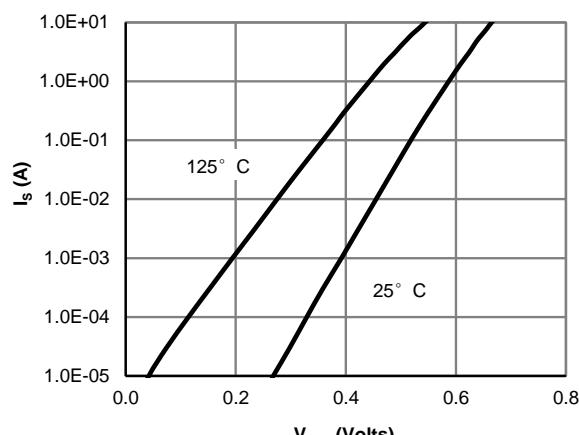
Note 2. PW <10 μs pulses, duty cycle 1% max.

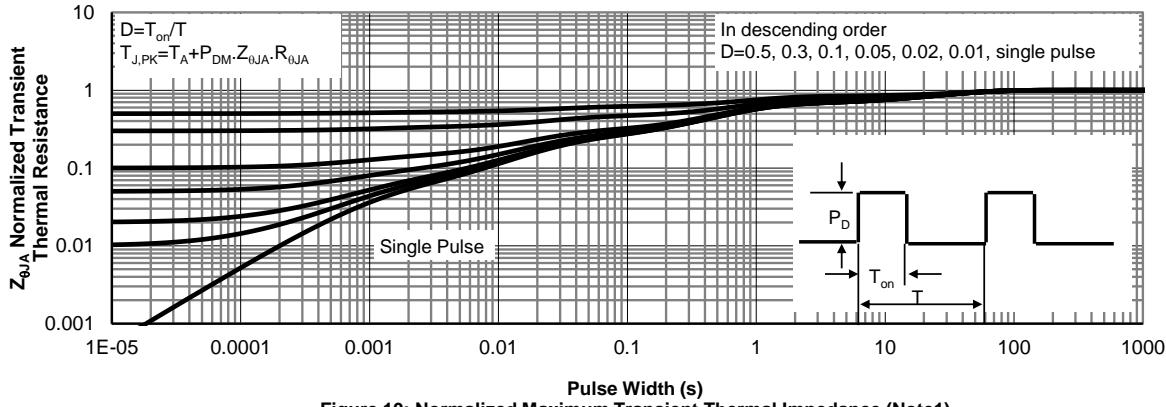
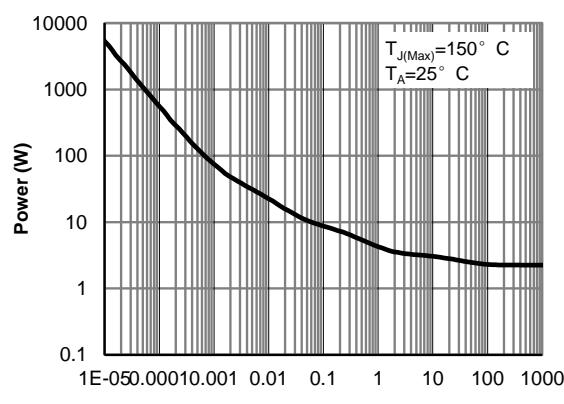
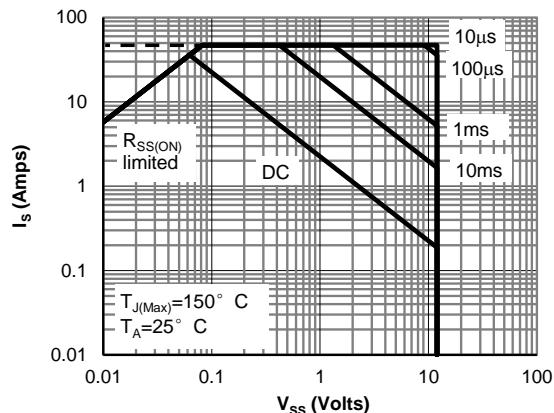
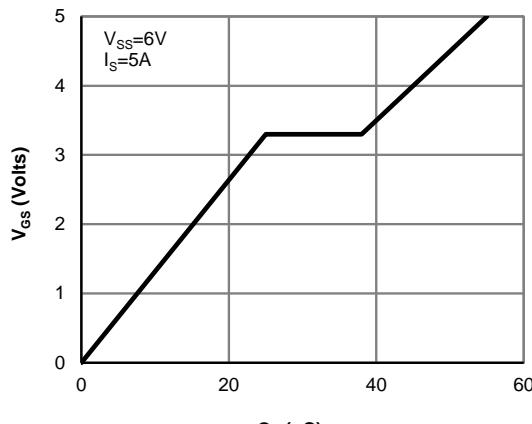
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{SSS}	Source-Source Breakdown Voltage	$I_S=250\mu\text{A}, V_{GS}=0\text{V}$	Test Circuit 6	12		V
I_{SSS}	Zero Gate Voltage Source Current	$V_{SS}=12\text{V}, V_{GS}=0\text{V}$	Test Circuit 1		1	μA
			$T_J=55^\circ\text{C}$		5	
I_{GSS}	Gate leakage current	$V_{SS}=0\text{V}, V_{GS}=\pm 8\text{V}$	Test Circuit 2		± 10	μA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{SS}=V_{GS}, I_S=250\mu\text{A}$	Test Circuit 3	0.4	0.8	1.2
		$V_{GS}=4.5\text{V}, I_S=5\text{A}$	Test Circuit 4	0.65	0.9	1.15
			$T_J=125^\circ\text{C}$	0.9	1.25	1.6
$R_{SS(\text{ON})}$	Static Source to Source On-Resistance	$V_{GS}=3.8\text{V}, I_S=5\text{A}$	Test Circuit 4	0.7	0.99	mΩ
		$V_{GS}=3.1\text{V}, I_S=5\text{A}$	Test Circuit 4	0.8	1.15	mΩ
		$V_{GS}=2.5\text{V}, I_S=5\text{A}$	Test Circuit 4	1.1	1.55	mΩ
g_{FS}	Forward Transconductance	$V_{SS}=5\text{V}, I_S=5\text{A}$	Test Circuit 3		40	S
V_{FSS}	Forward Source to Source Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	Test Circuit 5		0.6	V
DYNAMIC PARAMETERS						
R_g	Gate resistance	$f=1\text{MHz}$			1.8	KΩ
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, I_S=5\text{A}$			50	nC
$t_{D(on)}$	Turn-On DelayTime				4.5	μs
t_r	Turn-On Rise Time	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, R_L=1.2\Omega,$			10	μs
$t_{D(off)}$	Turn-Off DelayTime	$R_{\text{GEN}}=3\Omega$	Test Circuit 8		3.5	μs
t_f	Turn-Off Fall Time				22	μs

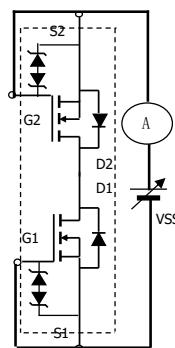
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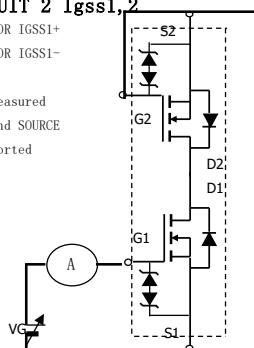
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Source Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Forward Source to Source Characteristics

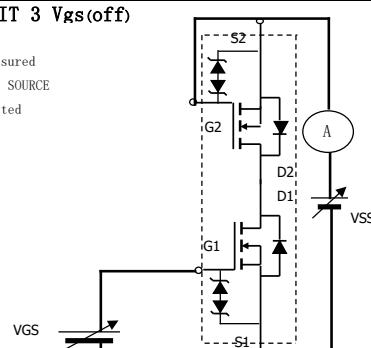
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


TEST CIRCUIT 1 Isss

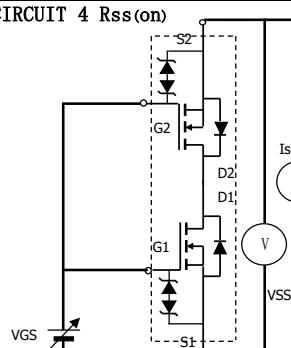
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 NEGATIVE VSS FOR ISSS-

TEST CIRCUIT 2 Igss1,2

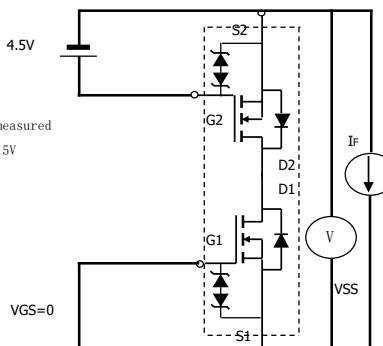
 POSITIVE VGS FOR IGSS1+
 NEGATIVE VGS FOR IGSS1-

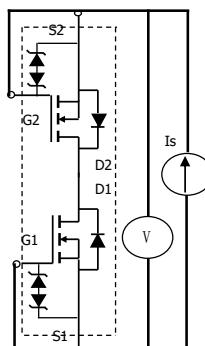
 When FET1 is measured
 between GATE and SOURCE
 of FET2 are shorted

TEST CIRCUIT 3 Vgs(off)

 When FET1 is measured
 between GATE and SOURCE
 of FET2 are shorted

TEST CIRCUIT 4 Rss(on)

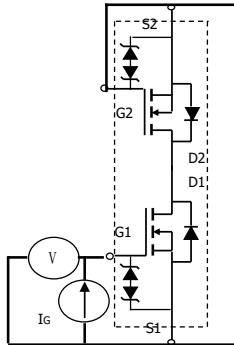
Vss/Is


TEST CIRCUIT 5 VF(ss)1,2

 When FET1 measured
 FET2 VGS=4.5V

TEST CIRCUIT 6 BVdss

 POSITIVE VSS FOR ISSS+
 NEGATIVE VSS FOR ISSS-

TEST CIRCUIT 7 BVgs01,2

 POSITIVE VSS FOR ISSS+
 NEGATIVE VSS FOR ISSS-

 When FET1 is measured
 between GATE and SOURCE
 of FET2 are shorted

**TEST CIRCUIT 8
Switching time**
